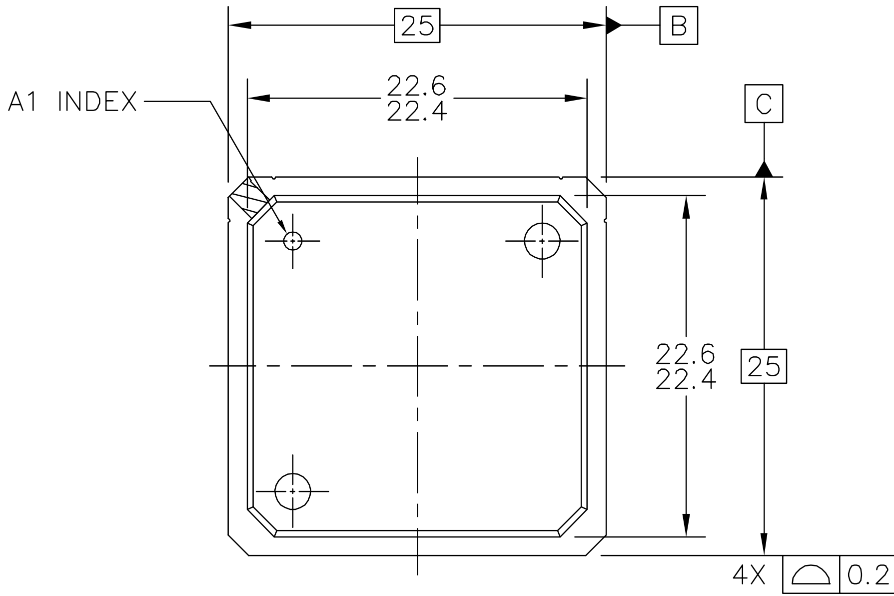

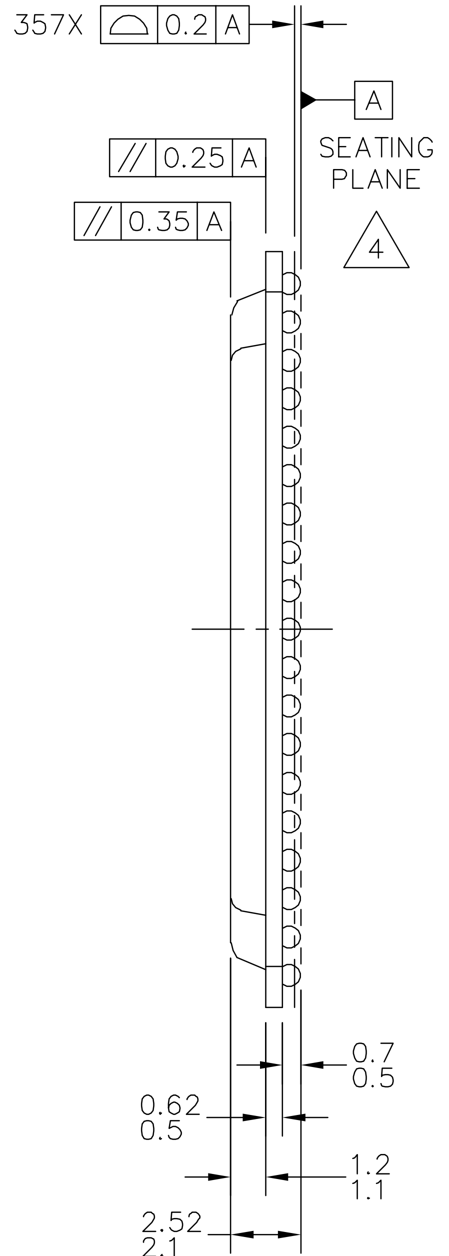

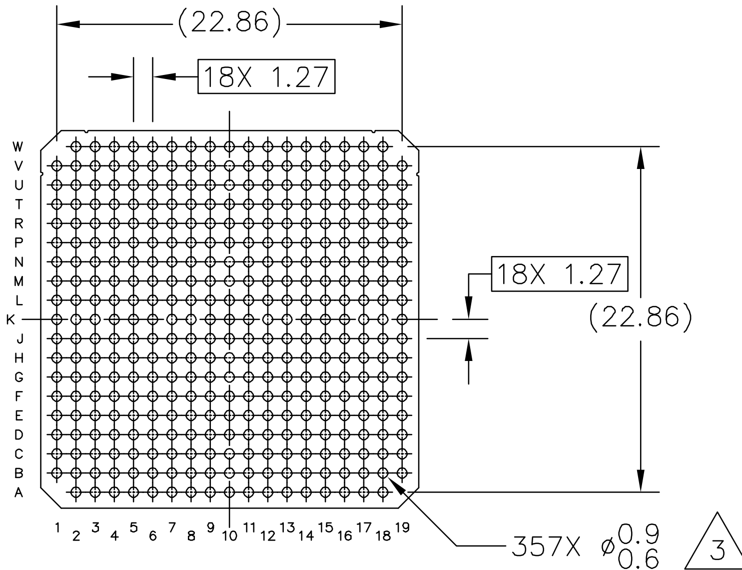

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TITLE: 357 I/O PBGA, 25 X 25 PKG, 1.27 MM PITCH	DOCUMENT NO: 98ASA99271D		REV: B
	CASE NUMBER: 1103D-03		22 APR 2005
	STANDARD: JEDEC MS-034 BAK-1		

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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